

Virtuous Cycle of AI

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3rd Annual Meeting of Heterogenous Integration Roadmap (IEEE EPS Chapter)
Milpitas, California Feb 20, 2020

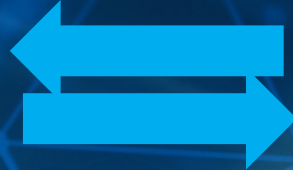


Machines:
Number Crunching
AND
Decision Making

Division of Labor Between Man and Machine Is Getting Disrupted:
Faster than Anyone Predicted!

The new frontier

Inside - Out



Outside - In

FROM
A WORLD OF
ANALYTICAL MODELS
Computational Fluid Dynamics

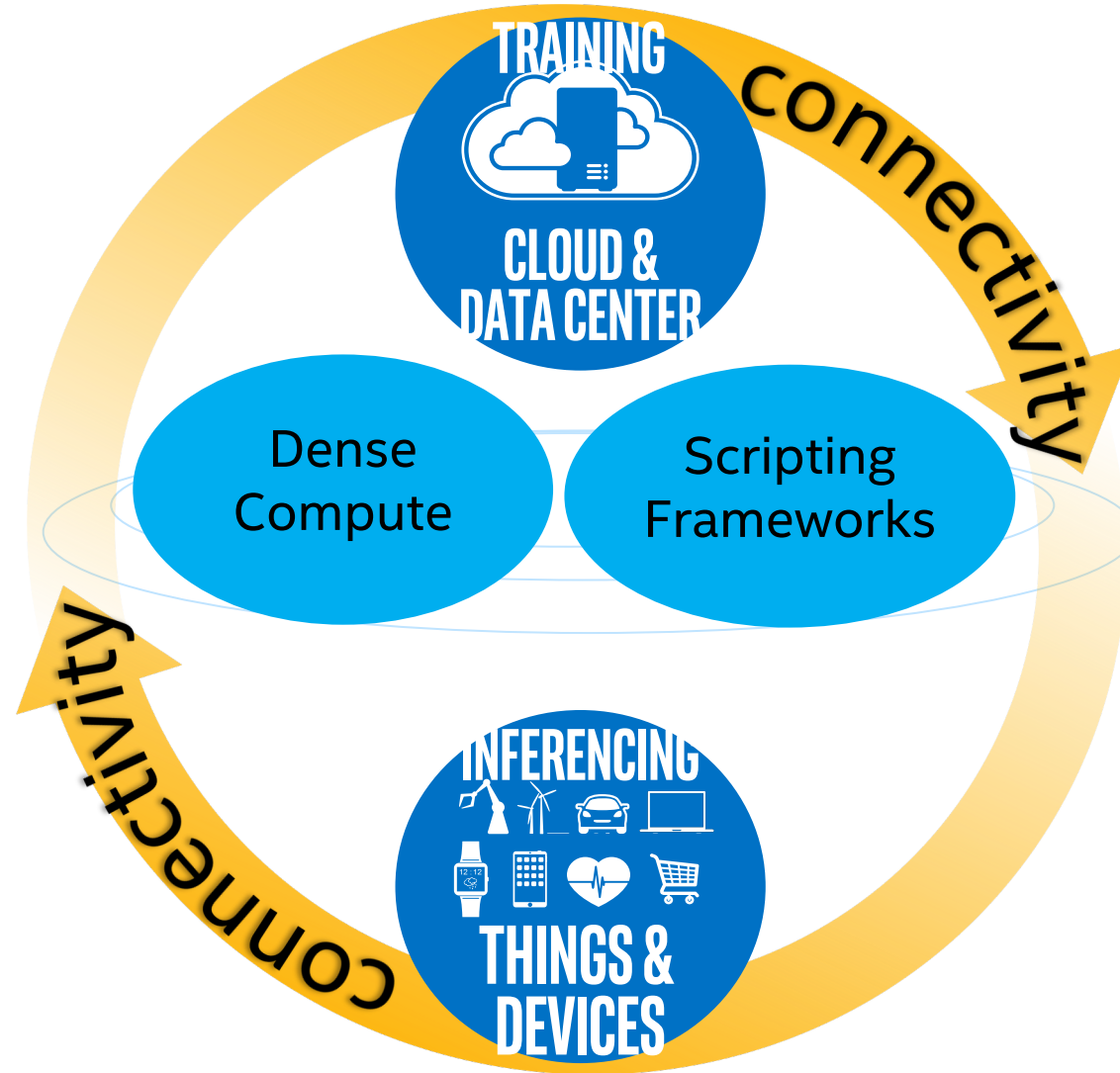
$$\mathbf{r} = \mathbf{r}(t) = r\hat{\mathbf{e}}_r$$
$$\mathbf{v} = v\hat{\mathbf{e}}_r + r\frac{d\theta}{dt}\hat{\mathbf{e}}_\theta + r\frac{d\varphi}{dt}\sin\theta\hat{\mathbf{e}}_\varphi$$
$$\mathbf{a} = \left(a - r\left(\frac{d\theta}{dt}\right)^2 \right)\hat{\mathbf{e}}_r + \left(r\frac{d^2\theta}{dt^2} + 2\frac{dr}{dt}\frac{d\theta}{dt} \right)\hat{\mathbf{e}}_\theta + \left(\frac{d^2\varphi}{dt^2}r\sin\theta + 2\frac{dr}{dt}\frac{d\varphi}{dt}\sin\theta + r\frac{d^2\varphi}{dt^2}\cos\theta \right)\hat{\mathbf{e}}_\varphi$$

TO
A WORLD OF DATA
DRIVEN MODELS
Event Detection from Social Media

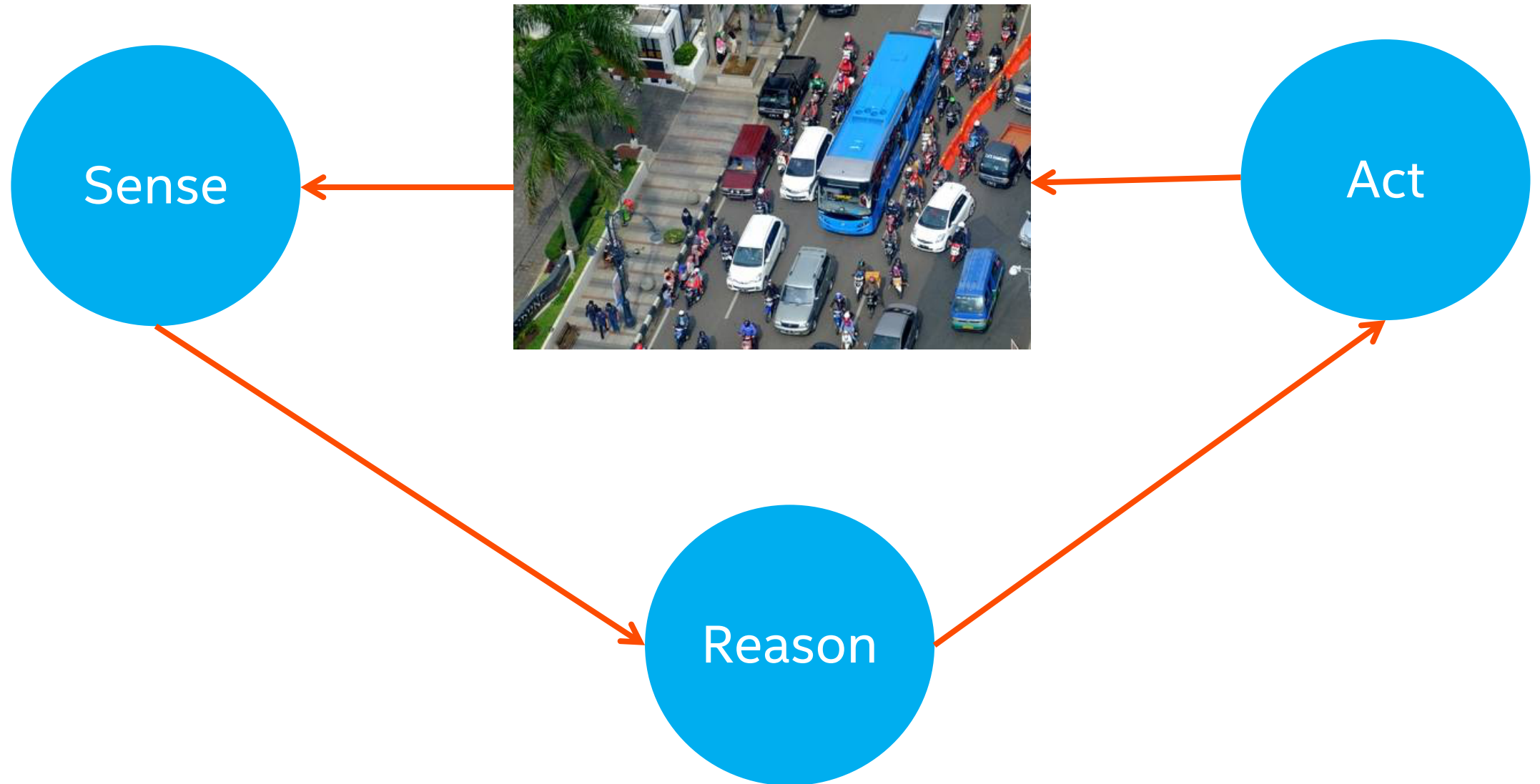
Start with Mathematical Model
Model → Simulate → Predict

Start with Data
Initial State → Increment → Steer

Virtuous Demand Cycle of AI Compute

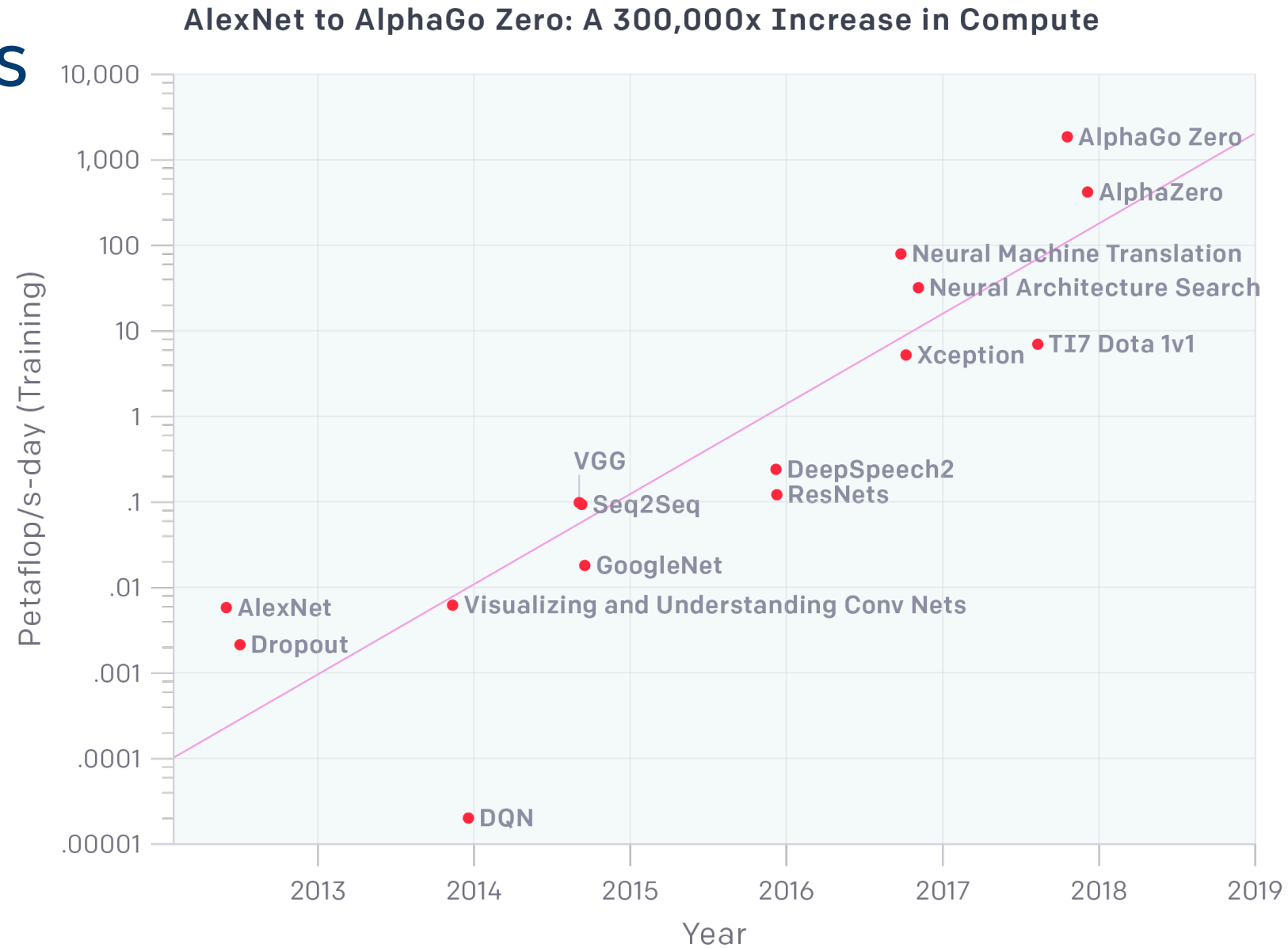


Virtuous Demand Cycle of Compute: A Functional View



AI Compute Needs

AlphaGo Zero needs:
2 EF-days to train →
Need a 100 ExaFlop machine
to train within an hour *

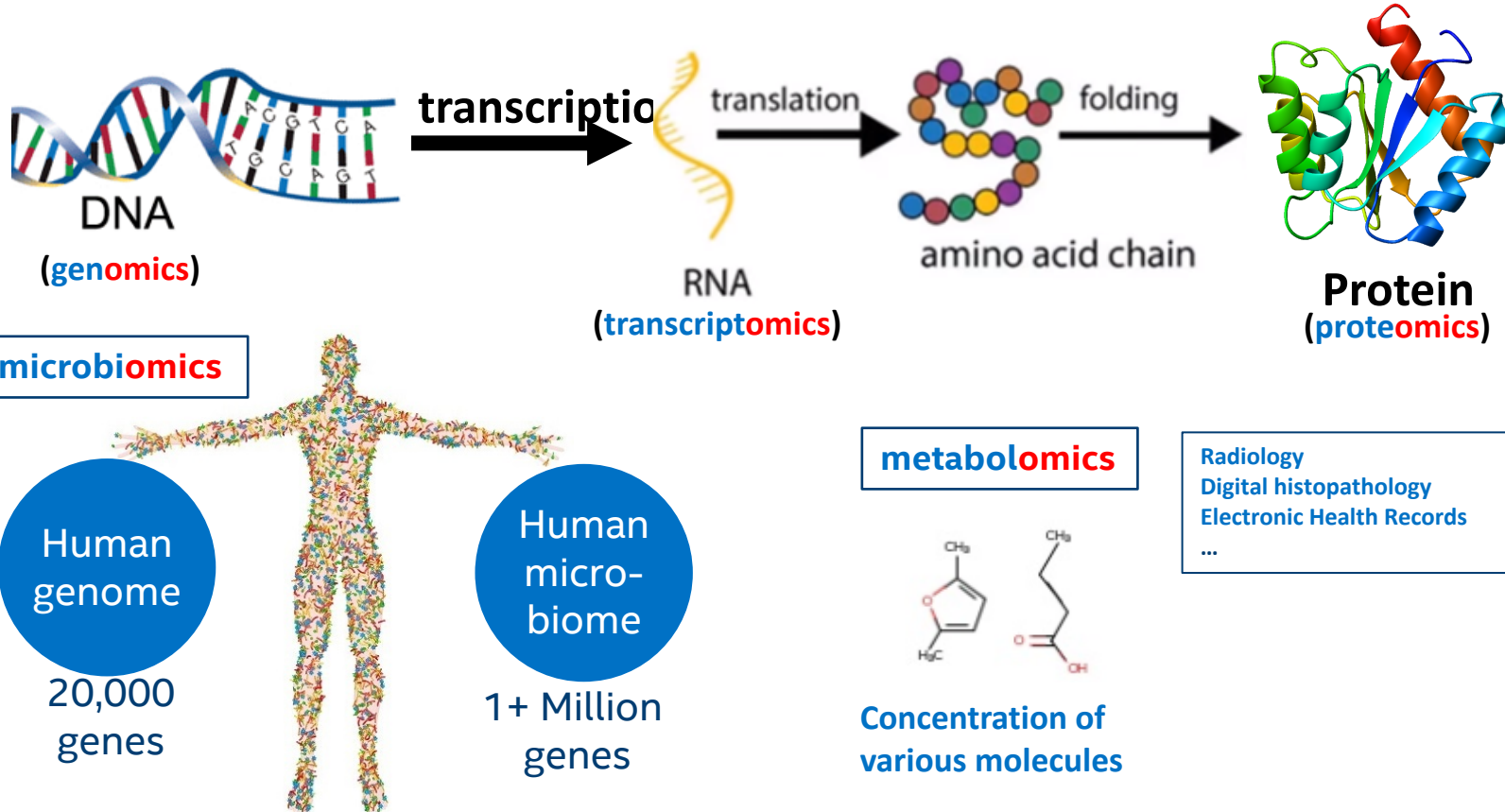


* <https://blog.openai.com/ai-and-compute/>

Illustrating population-scale AI in health sector

Explosion of trans-OMICS data in the coming decade

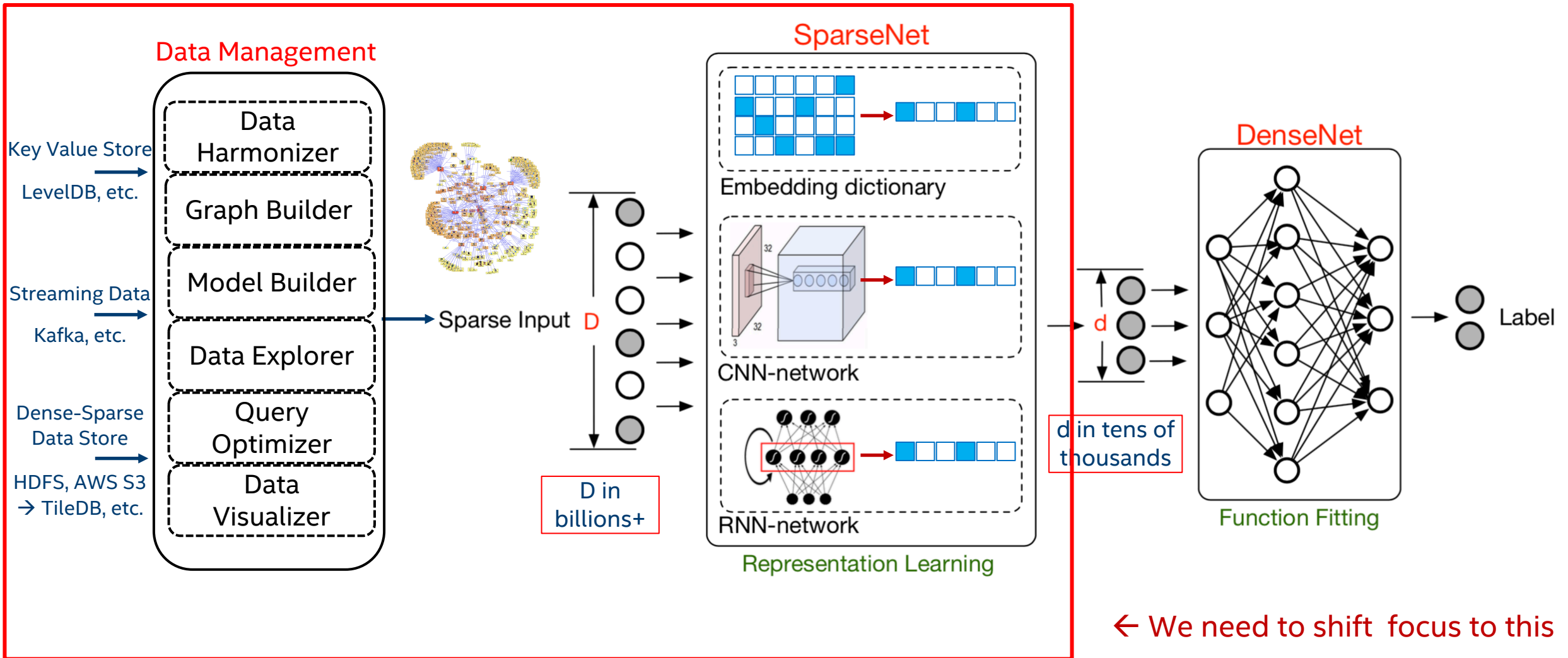
- From the molecular level to the genomic level to the organ level
- Interactions with medications, nutrients, therapeutic devices, and the environment.



Platform Characteristics

- **High throughput** omics pipeline over O(Billion) record data sets
- A multi-modal **AI pipeline** to correlate omics data across multiple datasets & generates actionable recommendations
- An open, modular **data-centric-computing platform** optimized for security, scalability and performance across many workloads
- 100s of exabytes of **storage capacity, processed in minutes** for results
- Best-in-class TCO with **easy to use/extend SW-Stack**

High-dimensional learning Infrastructure



Graph Analytics

Improve social-network analysis, fraud-ring detection, anomaly detection



CHALLENGES

- Sparse and irregular memory accesses
- Small data accesses with frequent synchronization
- Scaling to very large datasets

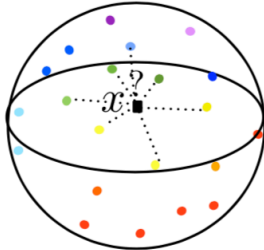
Real-Time Decision Making

Simplified ML Theory World View

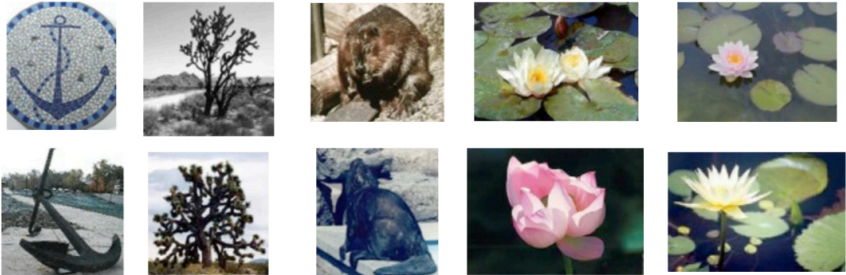
- If we only solve a single problem and design world-class hardware-software stack for it, what would that be:
- High Dimensional Learning
- “Learn a super-compact, deep (hierarchical) approximation of dynamic graphs – computable in polynomial time, and evolving very slowly in time”

Curse of Dimensionality

- $f(x)$ can be approximated from examples $\{x_i, f(x_i)\}_i$ by local interpolation if f is regular and there are close examples:



- Need ϵ^{-d} points to cover $[0, 1]^d$ at a Euclidean distance ϵ
 $\Rightarrow \|x - x_i\|$ is always large



Friday, October 3, 14

Credit for this slide above goes to Prof. Stephane Mallat *

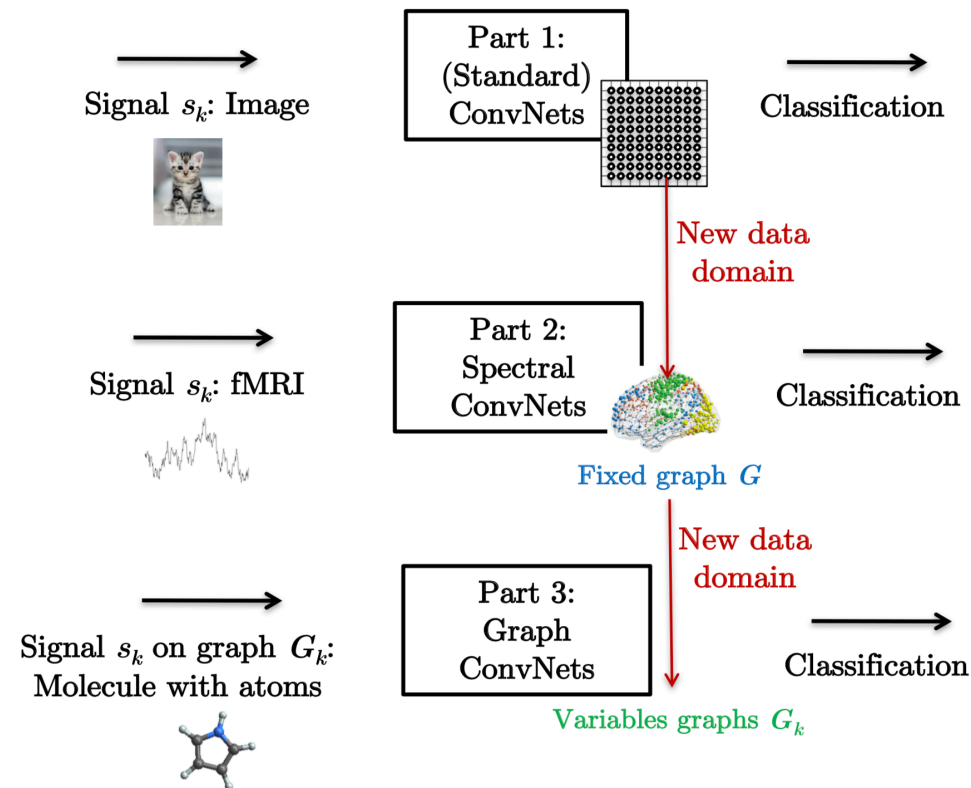
Recent (2017) Algorithmic Breakthrough: Geometric Deep Learning **

* High Dimensional Learning and Deep Neural Networks: <https://www.youtube.com/watch?v=nHXO43BqeQw>

** Geometric Deep Learning: Going beyond Euclidean data, by Michael Bronstein, John Bruna, Yann LeCun, Arthur Sxlam, Pierre Vandergheyn: <https://arxiv.org/pdf/1611.08097.pdf>

Will convolutions + downsampling prove effective in non-Euclidian space as well?

Graph ConvNet architectures



DARPA Graph Analytics Challenge

DARPA Taps Intel for Graph Analytics Chip Project

Michael Feldman | June 7, 2017 04:22 CEST

Intel shook hands with DARPA to craft HIVE Big Data platform a reality



SR Siliconreview Team
2017-06-09

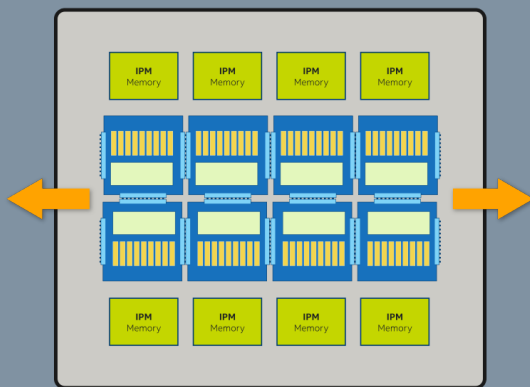
INTEL NAMED TO DARPA PROJECT FOCUSED ON MACHINE LEARNING AND ARTIFICIAL INTELLIGENCE

Intel has been selected by DARPA, a U.S. Department of Defense agency, to collaborate on the development of a powerful new data-handling and computing platform that will leverage machine learning and other artificial intelligence (AI) techniques.

PROGRAM TO DEVELOP
NEW TECHNOLOGIES TO REALIZE
1,000X PERFORMANCE-PER-
WATT GAINS IN THE ABILITY
TO HANDLE GRAPH ANALYTICS

Key Technologies and Scalability

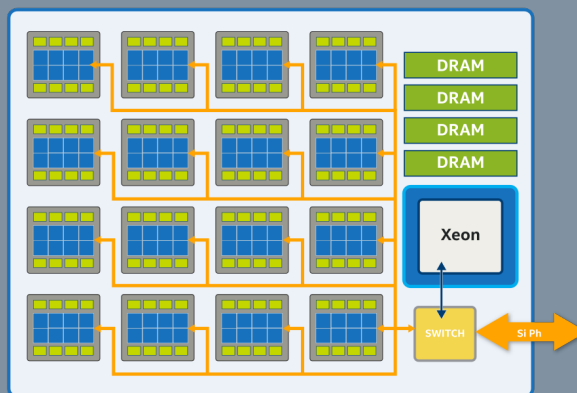
RE-IMAGINED ARCHITECTURE



CPU Support for Small,
Irregular Memory Accesses

Near-Memory Atomics

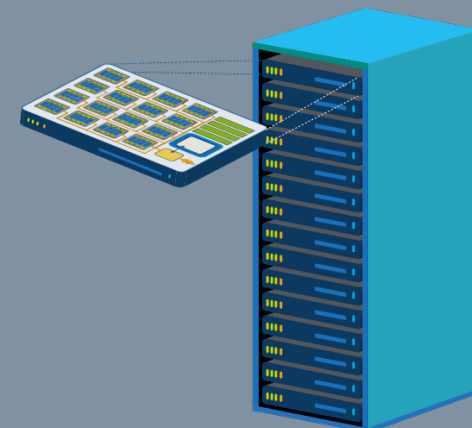
FULLY INTEGRATED



Global Memory Model

Packaging for High I/O and
Memory bandwidth

SEAMLESS SCALING

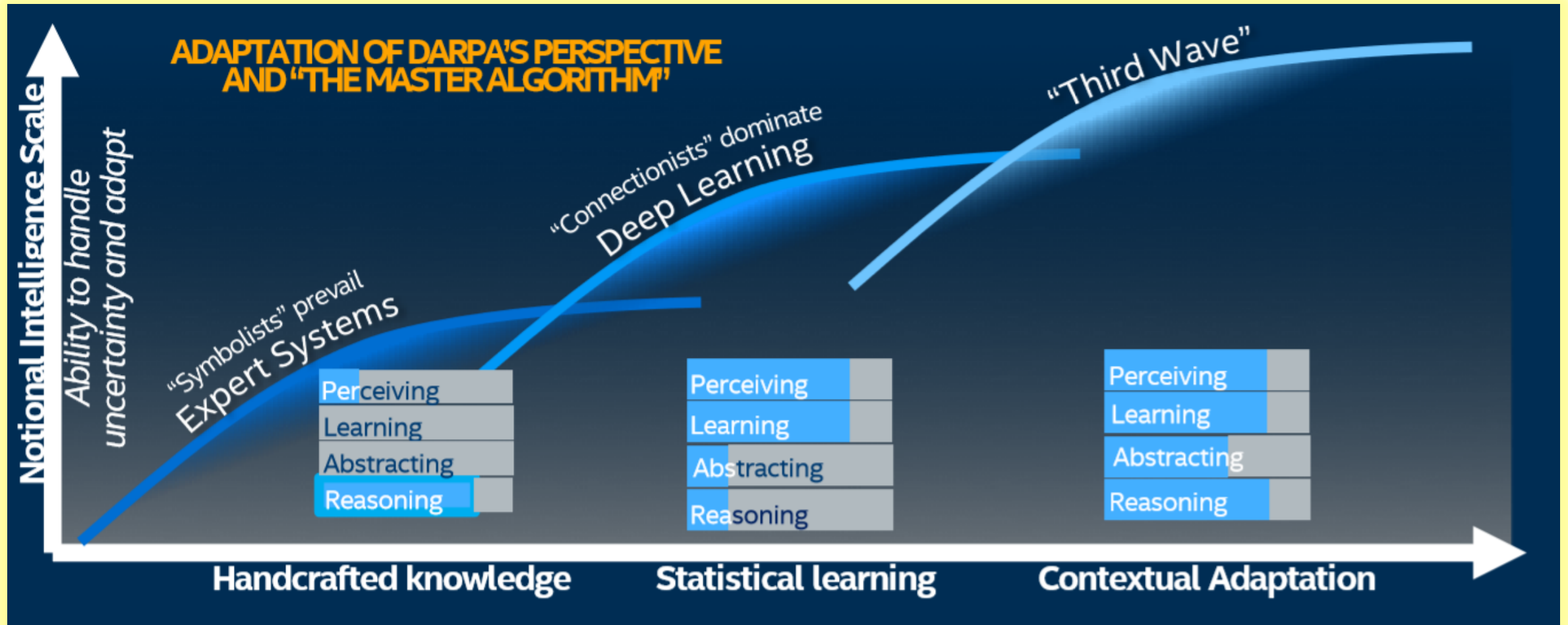


Network as 1st –class Citizen

Flatten Latency Hierarchy

Point-to-point Messages

The Future: Third Wave of AI

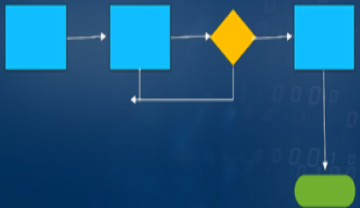


Deep Neural Networks Getting Augmented: NN + X + Memory
Such As: CNN + Bayes Net + Sparse Embeddings

LOOKING AHEAD ...

CONVENTIONAL

- Known procedures
- Generate answers



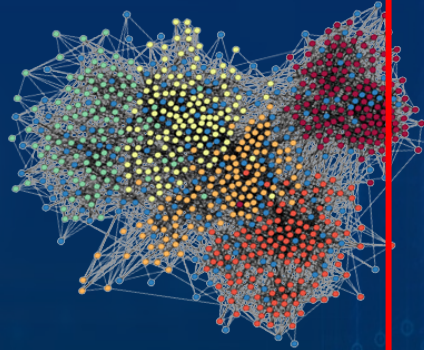
DEEP LEARNING

- Known answers
- Generate procedures with training



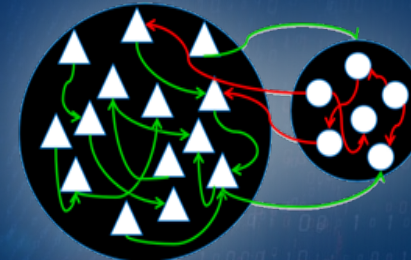
GRAPH ANALYTICS

- Graph edges and vertices represent relationships
- Big, sparse data structures



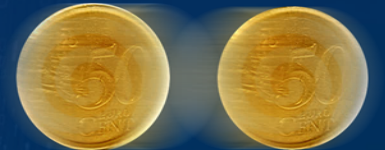
NEUROMORPHIC

- Many procedures
- Adapt the answer with reinforcement



QUANTUM

- Answers superimposed
- Select and measure the answer



What makes delivering AI hard and fun!

Better model building

LEARNING WITH LESS DATA AND SUPERVISION

DEEP NEURAL NETWORKS GETTING AUGMENTED: DATA-DRIVEN + ANALYTICAL + MEMORY

LEARNING MODELS THAT ARE EASIER TO REASON AND BETTER TO GENERALIZE

CONTINUOUS LEARNING FOR MISSION-CRITICAL AI

More efficient and pervasive model deployment

THROUGHPUT, ACCURACY, AND MODEL SIZE TRADEOFFS: SPARSIFICATION AND PRUNING

SELF-LEARNING AND PERSONALIZATION AT THE EDGE

Compute architecture needs of AI

REDUCING ARITHMETIC PRECISION WHILE PRESERVING ACCURACY

FEEDING THE COMPUTE ← MEMORY AND NETWORK; COMPUTE NEAR NETWORK

DOMAIN-SPECIFIC ARCHITECTURES → TRADITIONAL, SPATIAL, NEUROMORPHIC, QUANTUM

Productivity and Scaling needs of AI

STRONG-SCALING AI TO HPC SCALE ON CLOUD INFRASTRUCTURE: HIGHER-ORDER METHODS

DELIVERING PERFORMANCE-PRODUCTIVITY: FaaS AND NEW LANGUAGES AND ABSTRACTIONS

We have a problem though ...

Where Are All the Ninjas?

2019-01-17 / DEVELOPMENT

The Talent Shortage of Software Developers in 2019

1. According to [Code.org](#), there are less than 50,000 Computer Science graduates in 2017. But, there are over 500,000 open computing positions in the United States. This could mean that in 2020, the available seats for this position will exceed qualified applicants by a million which could widen the gap even more.

Only 10% of programmer pool have academic training to be *ninjas*
New additions to programming pool are data scientists
Hardware is getting increasingly complex for extracting high performance
Hence, *ninja gap* is not likely to go down!

Time to switch gear

From:

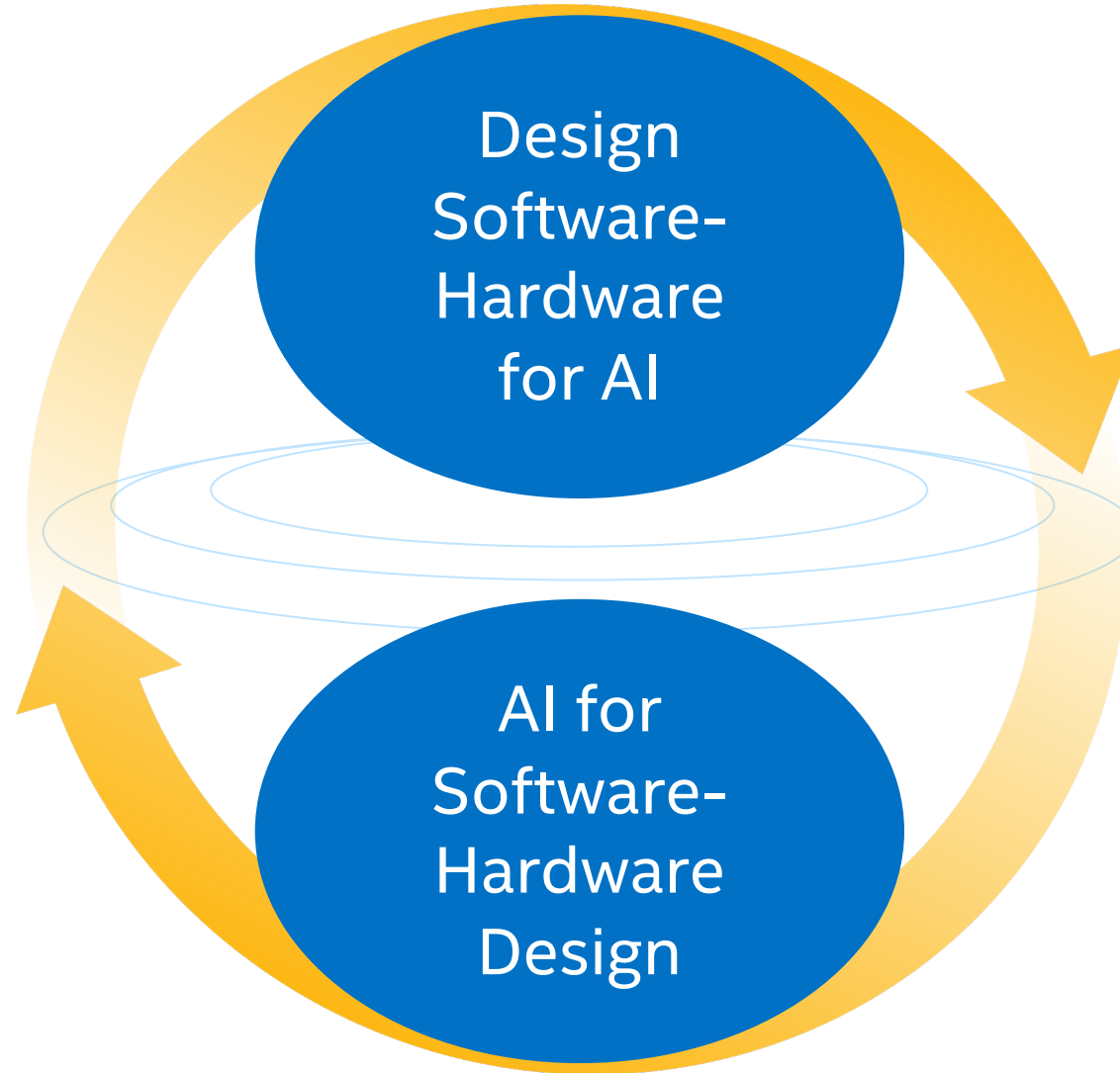
Designing hardware/software to meet AI needs

To:

AI helping us with our software-hardware needs

This implies a virtuous cycle for realized AI performance growth!

Virtuous Supply Cycle of AI Compute



MACHINE PROGRAMMING

**ANY TECHNIQUE THAT AUTOMATES SOME ASPECT OF
SOFTWARE (AND HARDWARE) DEVELOPMENT.**

ENABLE THE WORLD TO CREATE SOFTWARE.



The Machine Programming Inflection Point

- **ML/DL algorithms**

- Transformer, neural recursion, DeepCoder, time series precision and recall, ...

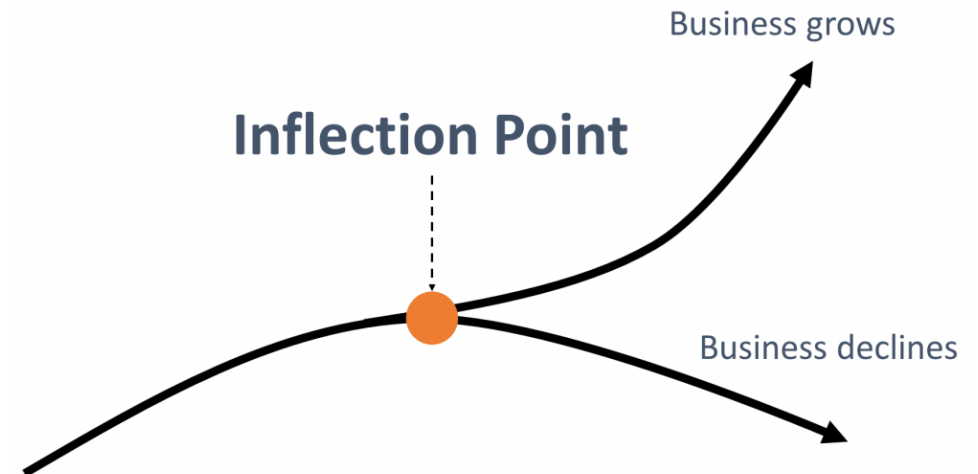
- **Parallel hardware**

- CPU, GPU, NNP, TPU, FPGAs, ...

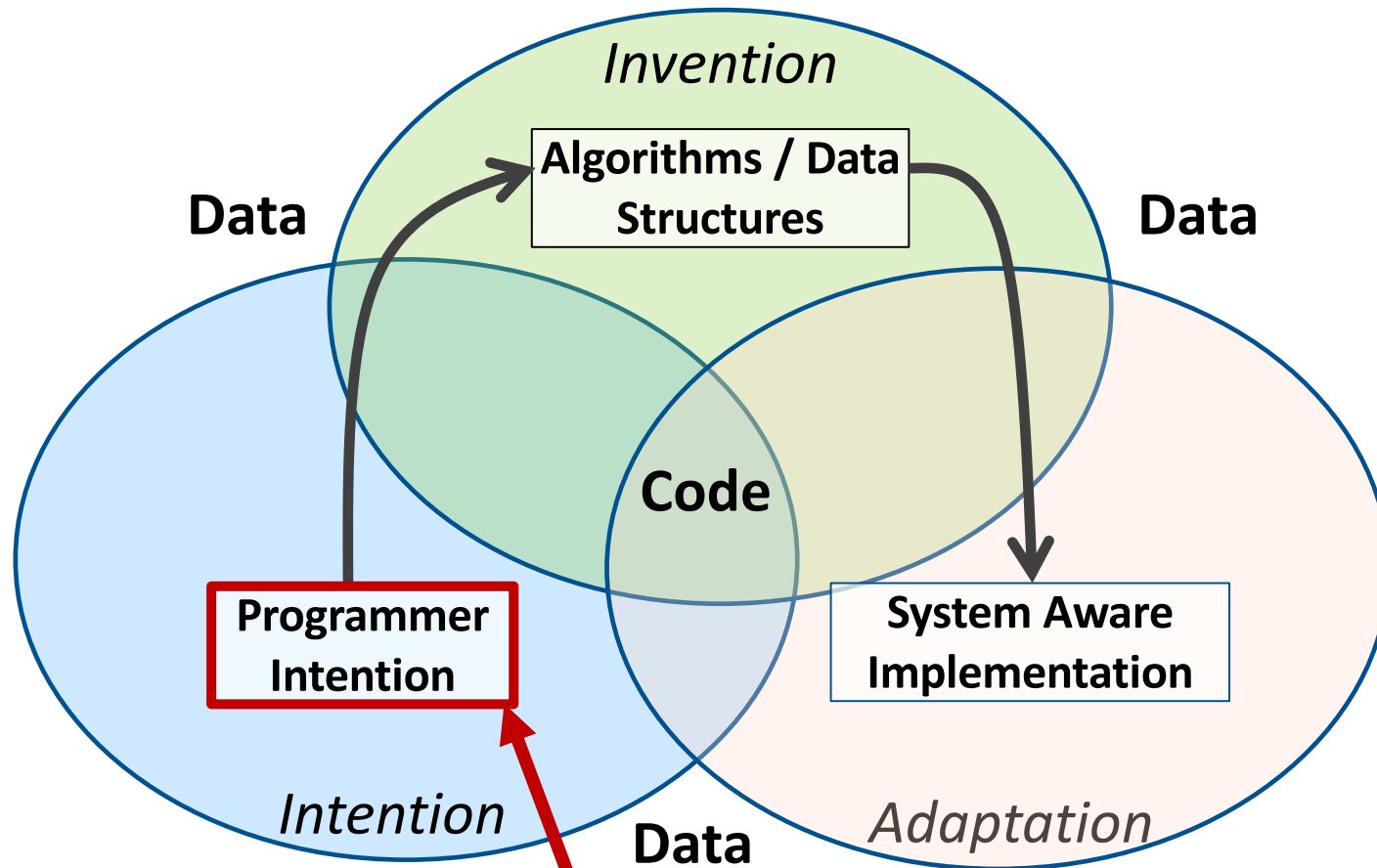
- **Rich & dense programming data**

- 33,000 github repos in 2008
- 180,000,000 github repos in 2019

- *And programs are graphs after all*



Three Pillars of Machine Programming *

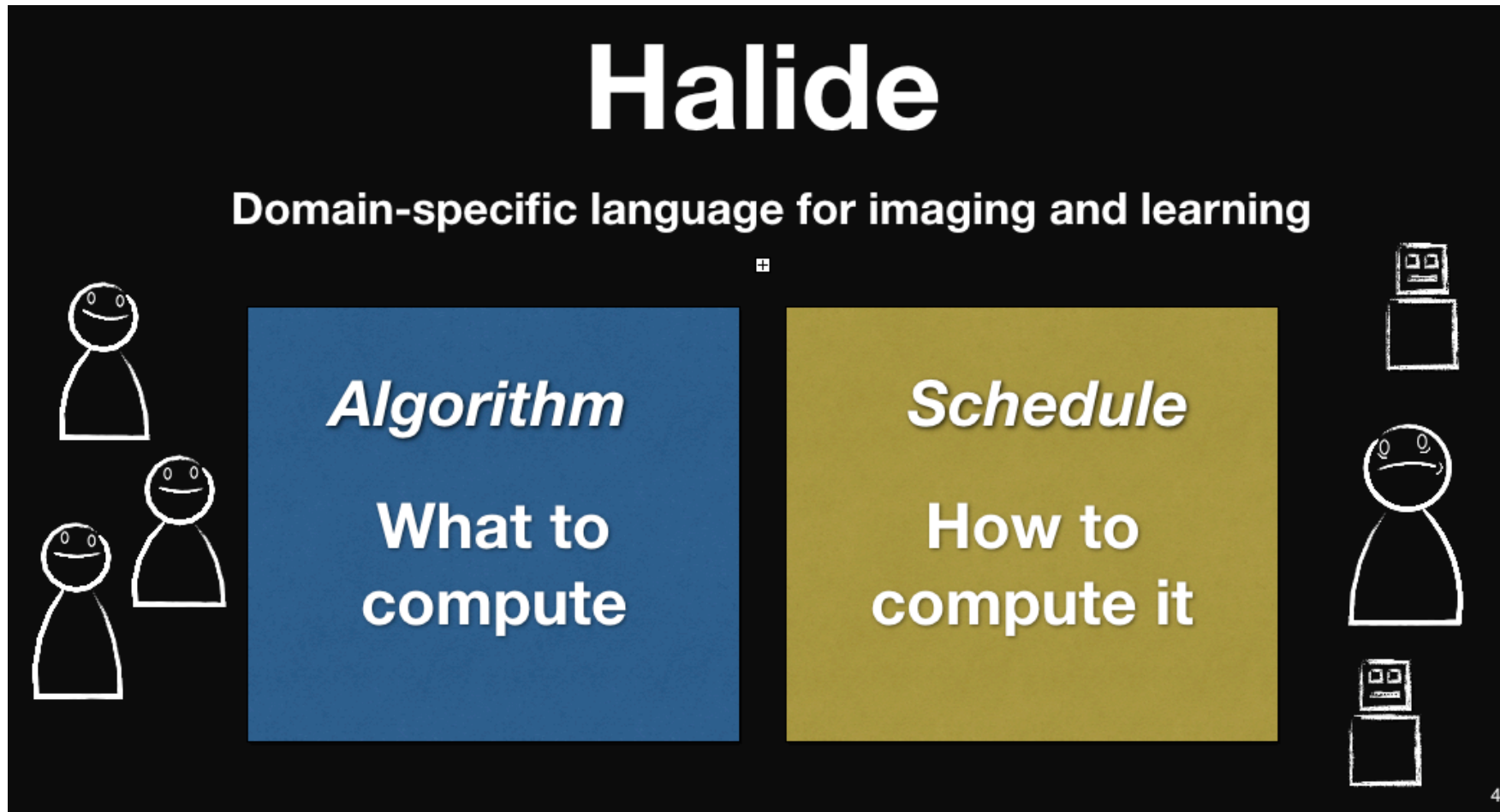


* Justin Gottschlich, Intel
Armando Solar-Lezama, MIT
Nesime Tatbul, Intel
Michael Carbin, MIT
Martin Rinard, MIT
Regina Barzilay, MIT
Saman Amarasinghe, MIT
Joshua B Tenenbaum, MIT
Tim Mattson, Intel

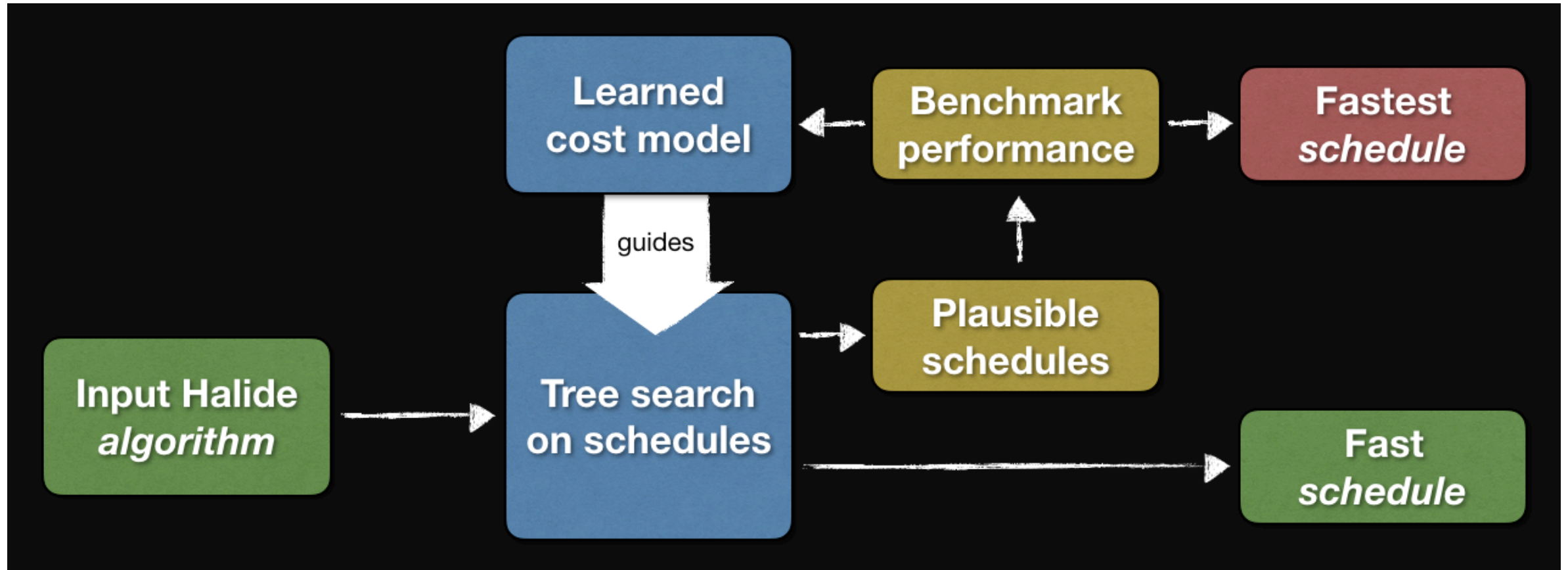
ACM SIGPLAN Workshop on
Machine Learning and
Programming Languages (MAPL),
PLDI'18,
arxiv.org/pdf/1803.07244.pdf

The programmer only does this.

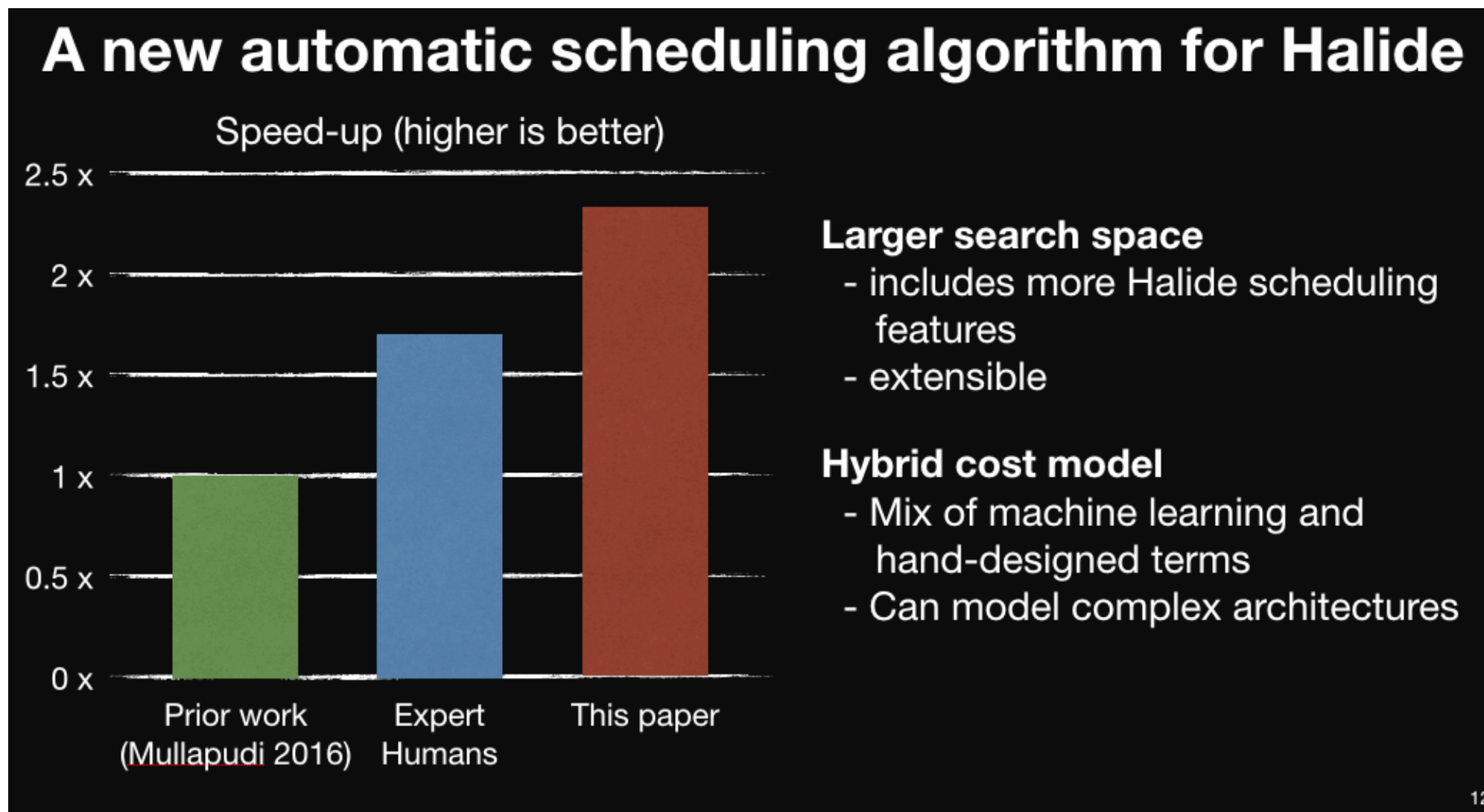
Learning to Optimize Halide with Tree Search and Random Programs *



Halide Learned System Design



Significantly Outperforms Human Ninjas



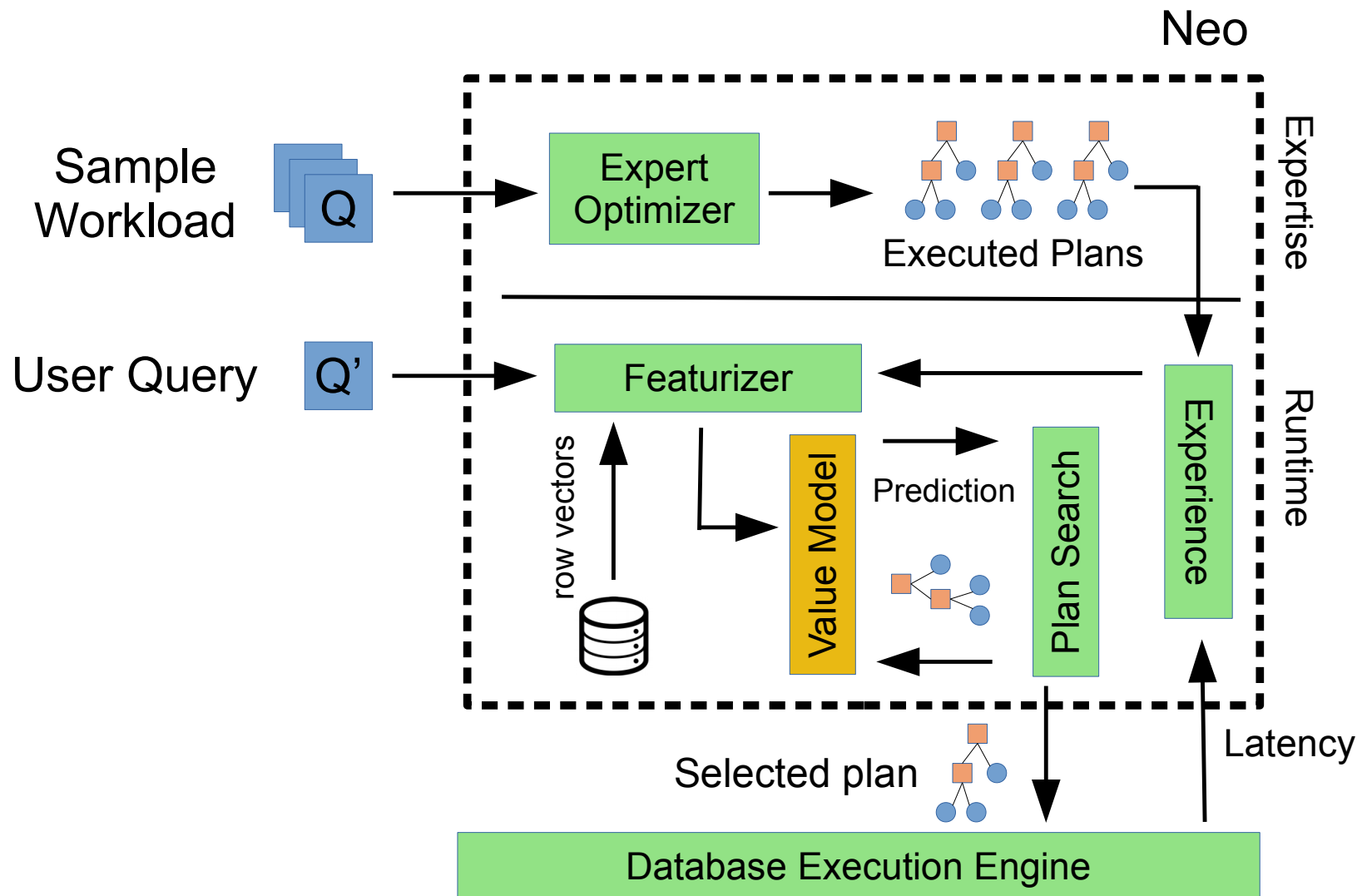
Neo: A Learned end-to-end Query Optimizer *

Traditional Optimizers vs. Neural Optimizer

	Traditional Optimizers	Neural Optimizer (Neo)
Creation	Human developers	Learning from demonstration, Reinforcement learning
Query Representation	Operator tree	Tree with feature encodings
Cost Model	Hand-crafted model	Learned DNN model (value network)
Plan Space Search	Enumeration, Heuristics, Dynamic programming	DNN-guided search strategy (best-first)
Cardinality Estimation	Histograms, Hand-crafted models	Histograms, Learned embeddings (row vectors)

Neo: first fully learned end-to-end solution to DB query optimization:
Matches/exceeds state of the art open-source & commercial optimizers within 24 hrs of training

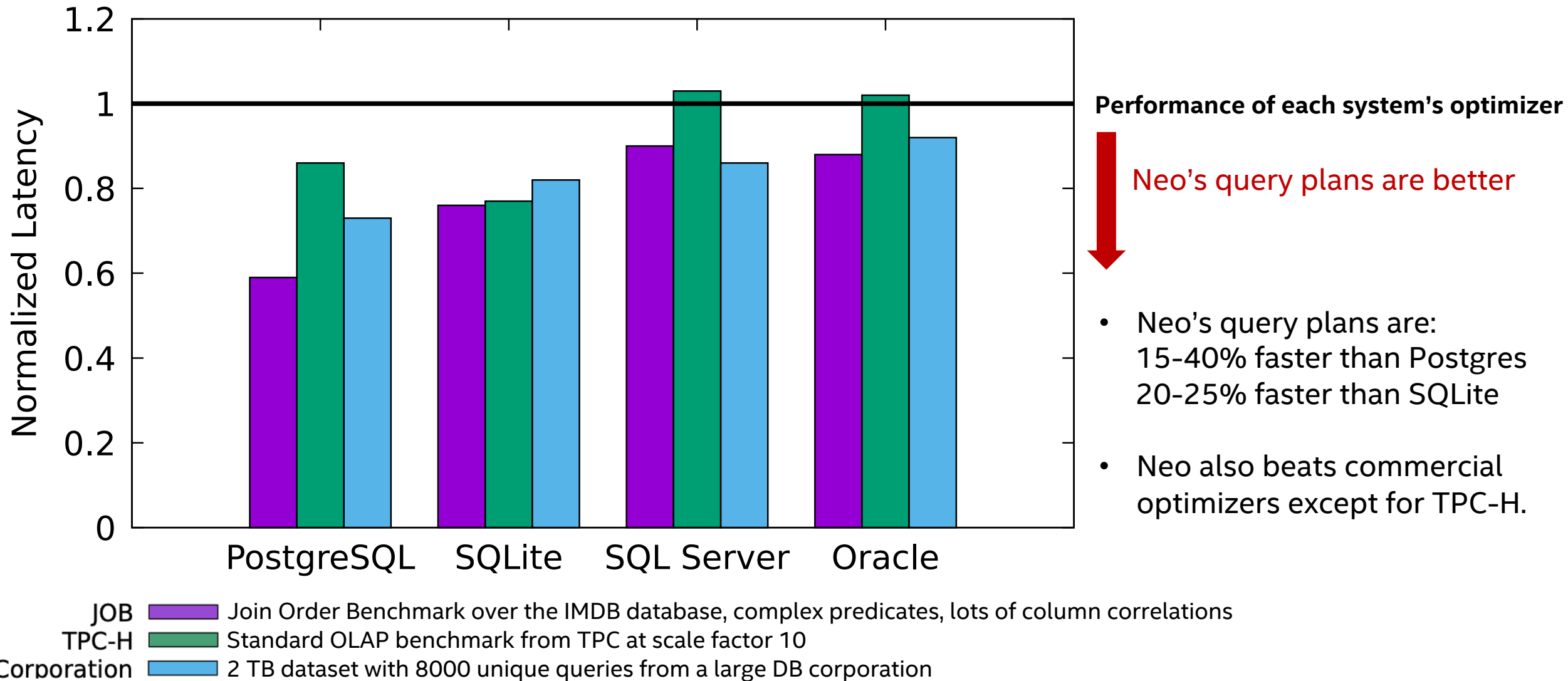
Neo's Learning Framework



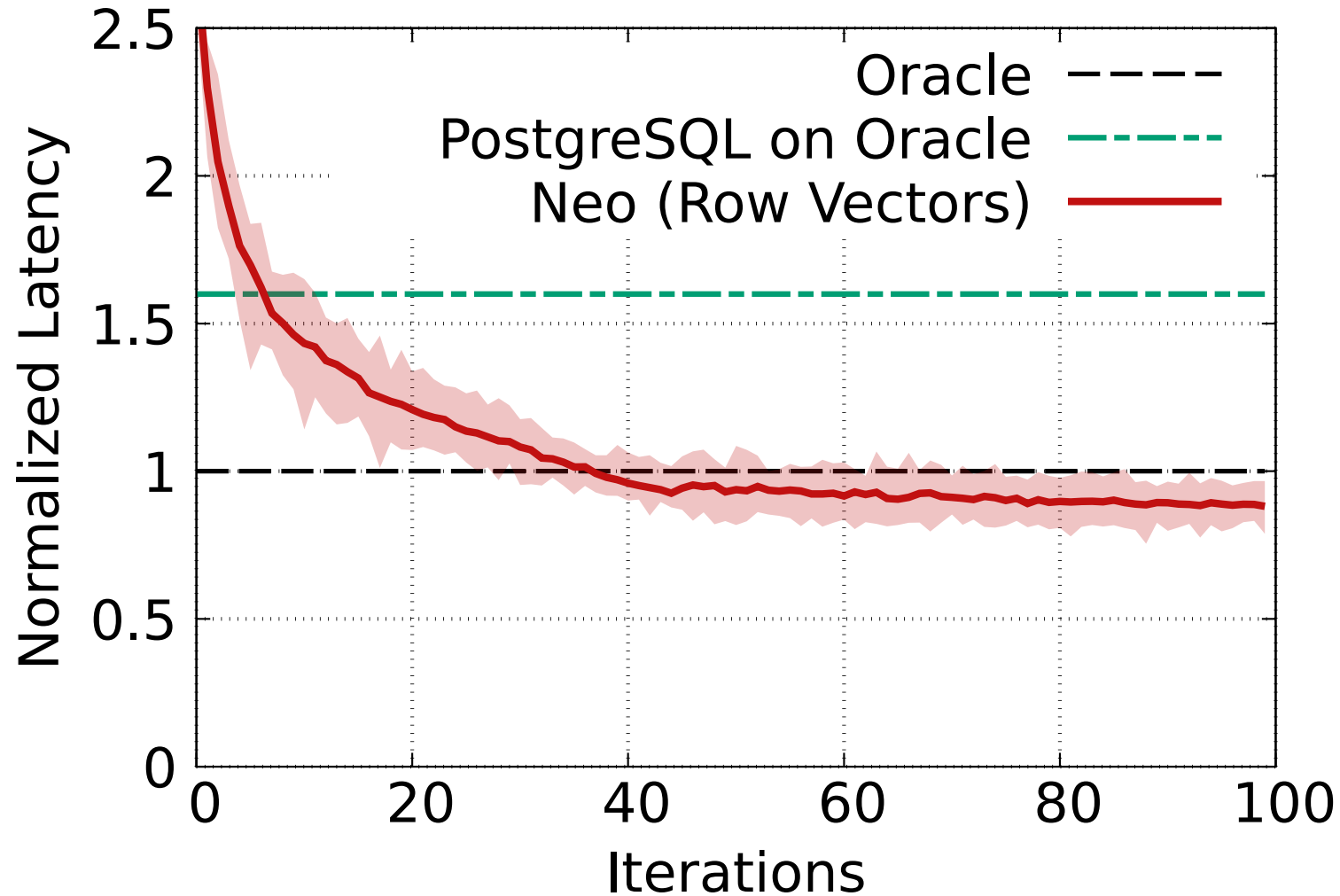
Key ingredients:

- Learning from demonstration
- Value Model: DNN based on tree convolution
- Reinforcement learning
- Query and plan level feature encoding techniques (e.g., row-vectors that capture predicate semantics)

Neo vs. Traditional Optimizers: Overall Performance



Neo vs. Oracle Optimizer: Learning Curve





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October 03 '18

Google, Intel and Microsoft team up w/CSAIL on new data-driven initiative

WRITTEN BY

[Adam Conner-Simons](#)



RELATED

[DSAIL homepage](#)

[CSAIL Alliances program](#)

[Tim Kraska](#)

DSAIL Launched Jan 2019 @ MIT in collaboration with Google-Microsoft [<link>](#)

Summary

We are at an unprecedented convergence of massive
compute with massive data ...

This confluence will have a lasting impact on both how
we do computing and what computing can do for us!

Questions?

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